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## **SPECIFICATION**

- Supplier : Samsung electro-mechanics
- Product : Multi-layer Ceramic Capacitor
- Samsung P/N : CL10B475KQ8NQNC
- Description : CAP, 4.7 µF, 6.3V, ±10%, X7R, 0603

A. Samsung Part Number

		<u>CL</u>	<u>10</u>	<u>B</u>	<u>475</u>	<u>K</u>	<u>Q</u>	<u>8</u>	<u>N</u>	<u>Q</u>	<u>N</u>	<u>C</u>
		1	2	3	4	5	6	1	8	9	10	1
	Cariaa	Comound Mul		Cor								
1	Series	Samsung Multi-layer Ceramic Capacitor										
2	Size	0603 (inch	code)		L:	1.6	± 0.1	5	mm		W:	0.8 ± 0.15 mm
3	Dielectric	X7R				8	Inne	r ele	ctroc	le		Ni
4	Capacitance	<b>4.7</b> μF					Tern	ninat	tion			Cu
5	Capacitance	±10 %					Plati	ng				Sn 100% (Pb Free)
	tolerance					9	Proc	luct				0603 Size dimension spec
6	Rated Voltage	6.3 V				10	Spee	cial				Reserved for future use
$\bigcirc$	Thickness	0.8 ± 0.1	5 mm			1	Pacl	cagir	ng			Cardboard Type,7"reel(4,000ea)

## B. Samsung Reliability Test and Judgement condition

	Performance	Test condition						
Capacitance	Within specified tolerance	1ktz±10% 0.5±0.1Vrms						
Tan δ (DF)	0.1 max.	]						
Insulation	More than 100Mohm⋅ <i>μ</i> F	Rated Voltage 60~120 sec.						
Resistance								
Appearance	No abnormal exterior appearance	Visual inspection						
Withstanding	No dielectric breakdown or	250% of the rated voltage						
Voltage	mechanical breakdown							
Temperature	X7R							
Characteristics	(From -55 $^{\circ}$ C to 125 $^{\circ}$ C, Capacitance change should be within ±15%)							
Adhesive Strength	No peeling shall be occur on the	500g·F, for 10±1 sec.						
of Termination	terminal electrode							
Bending Strength	Capacitance change : within ±12.5%	Bending to the limit (1mm)						
		with 1.0mm/sec.						
Solderability	More than 75% of terminal surface	SnAg3.0Cu0.5 solder						
	is to be soldered newly	245±5℃, 3±0.3sec.						
		(preheating : 80~120°C for 10~30sec.)						
Resistance to	Capacitance change : within ±7.5%	Solder pot : 270±5°C, 10±1sec.						
Soldering heat	Tan δ, IR : initial spec.							

	Performance	Test condition				
Vibration Test	Capacitance change : within ±5%	Amplitude : 1.5mm				
	Tan δ, IR : initial spec.	From 10H₂ to 55H₂ (return : 1min.)				
		2hours $\times$ 3 direction (x, y, z)				
Moisture	Capacitance change : within ±12.5%	With rated voltage				
Resistance	Tan δ: 0.125 max	40±2℃, 90~95%RH, 500+12/-0 hours.				
	IR ∶ More than 12.5MΩ· <i>μ</i> F					
High Temperature	Capacitance change : within ±12.5%	With 100% of the rated voltage				
Resistance	Tan δ: 0.125 max	Max. operating temperature				
	IR : More than 25MΩ· <i>μ</i> F					
		1000+48/-0 hours.				
Temperature	Capacitance change : within ±7.5%	1 cycle condition				
Cycling	Tan δ, IR : initial spec.	Min. operating temperature $\rightarrow$ 25 °C				
		$\rightarrow$ Max. operating temperature $\rightarrow$ 25 °C				
		5 cycles test				

## C. Recommended Soldering method :

Reflow ( Reflow Peak Temperature : 260+0/-5°C, 10sec. Max )

\* For the more detail Specification, Please refer to the Samsung MLCC catalogue.